

Appl. No. 10/616,528

Attorney Docket No. 10541-1847

**I. Listing of Claims**

1. (Currently Amended) A microelectronic package comprising:

a housing including a cylindrical wall defining a central axis, the wall having an outer wall surface about an axis and an inner wall surface, said cylindrical wall defining a central compartment between the inner surface and the central axis, said inner wall surface having at least one assembly support surface that substantially faces the central axis, said housing further including at least one axial channel interposed between the outer wall and the inner wall; and

a microelectronic assembly affixed to the assembly support surface, thereby disposing the microelectronic assembly within the central compartment.

2. (Original) The microelectronic package of claim 1 wherein the inner wall is non-concentric with the outer wall.

3. (Original) The microelectronic package of claim 1 wherein the support surface is planar.

4. (Previously Amended) The microelectronic package of claim 1 wherein the inner wall comprises first and second assembly support surfaces that are planar, wherein the microelectronic package comprises a first microelectronic assembly affixed to the first assembly support surface, a

BRINKS  
HOFER  
GILSON  
LIONE

BRINKS HOFER GILSON & LIONE  
PO Box 10395  
Chicago, IL 60610-5599

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second microelectronic assembly affixed to the second assembly support surface, and a flexible interconnect connecting the first microelectronic assembly and the second microelectronic assembly.

5. (Original) The microelectronic package of claim 1 wherein the channel is adapted for conveying cooling gas through the housing.

6. (Original) The microelectronic package of claim 1 wherein the housing comprises a first section having first axial edges and a second section having second axial edges joined to the first axial edges.

7. (Original) The microelectronic package of claim 6 wherein the first section comprises a semi-cylindrical wall and wherein the second section comprises a semi-cylindrical wall.

8. (Original) The microelectronic package of claim 1 wherein the housing is formed by a metal extrusion.

9. (Original) The microelectronic package of claim 1 wherein the housing is formed of a metal casting.

10. (Original) The microelectronic package of claim 1 wherein the housing is received in a tubular casing.

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11. (Original) The microelectronic package of claim 1 wherein the support surface is a curve having a radius of curvature less than the radius of the outer wall.



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Chicago, IL 60610-5599

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